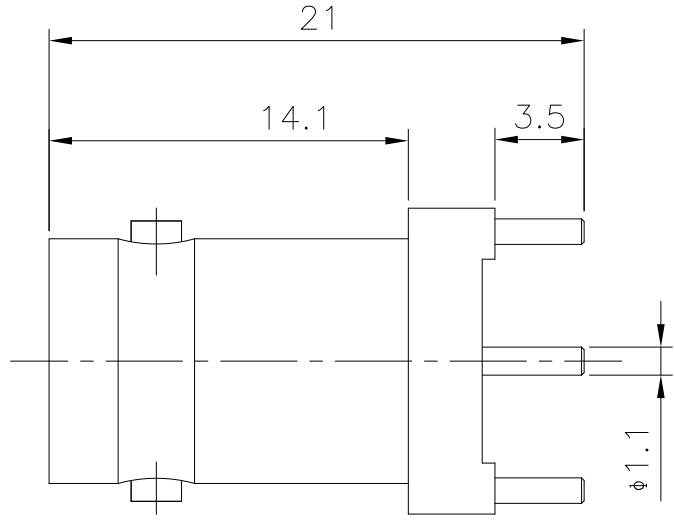
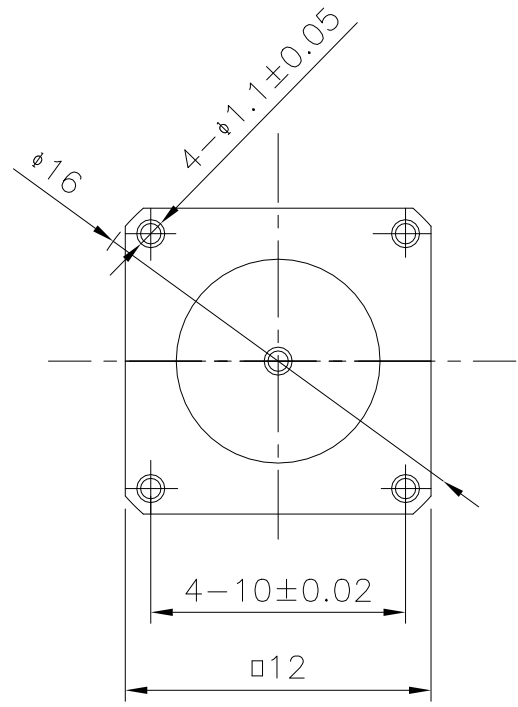


REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
1			INITIAL RELEASE	24/01.05	Yy_D
3			UPDATE P/N	24/04,08	Yy_D



技术要求:

- 产品外导体材质: HPb59-1, 表面镀镍2um;  
内导体材质: 锡磷青铜(QSn6.5-0.1), 表面镀金0.15um;  
介质: PEFE
- 材质满足RoHS要求;
- 中心接触电阻:  $\leq 2M\Omega$ , 外接触电阻  $\leq 1M\Omega$ ;
- 工作温度范围:  $-55^{\circ}C \sim 155^{\circ}C$ ;
- 未注线性尺寸公差按GB/T1804-m;
- 满足盐雾: 96H

电气/机械指标要求

阻抗	频率(GHz)	VSWR<	IL<	PIM<	耐压	绝缘电阻>
50 $\Omega$	0.3GHz	/	/	/	1600V	5000M $\Omega$

5704BZ-025R0000R-TJ

T: TRAY  
R: REEL  
R:RoHS  
H:HALOGEN-FREE  
BNC

DIM	TOL	DIM	TOL		DEREN			
X.	$\pm 0.35$	X.	$\pm 2'$		SHENZHEN DEREN ELECTRONIC CO., LTD			
.X	$\pm 0.30$	.X	$\pm 1'$	C-DWG:	TJ	DATE	TITLE: BNC HN-KSY CONN	
.XX	$\pm 0.25$			DRAW NO.	DESIGN: Yy_D	24/04,08	P/N:	
				SCXXXXXXXX-X	CHECK:		SHEET: 1/1	
				REV. 3	APPROVAL:		SCALE: N/A UNIT: mm	